

PROS

could use
exp 100% AL
could easily
get substrate
content

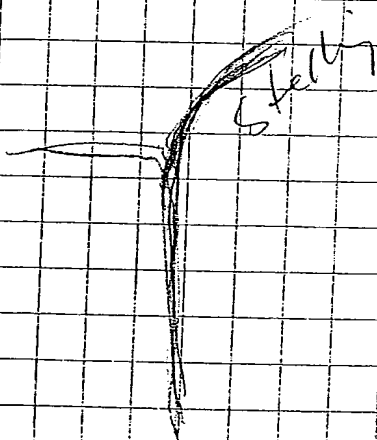
A soda is
piece of cake

get your money's
worth on STS

CONS

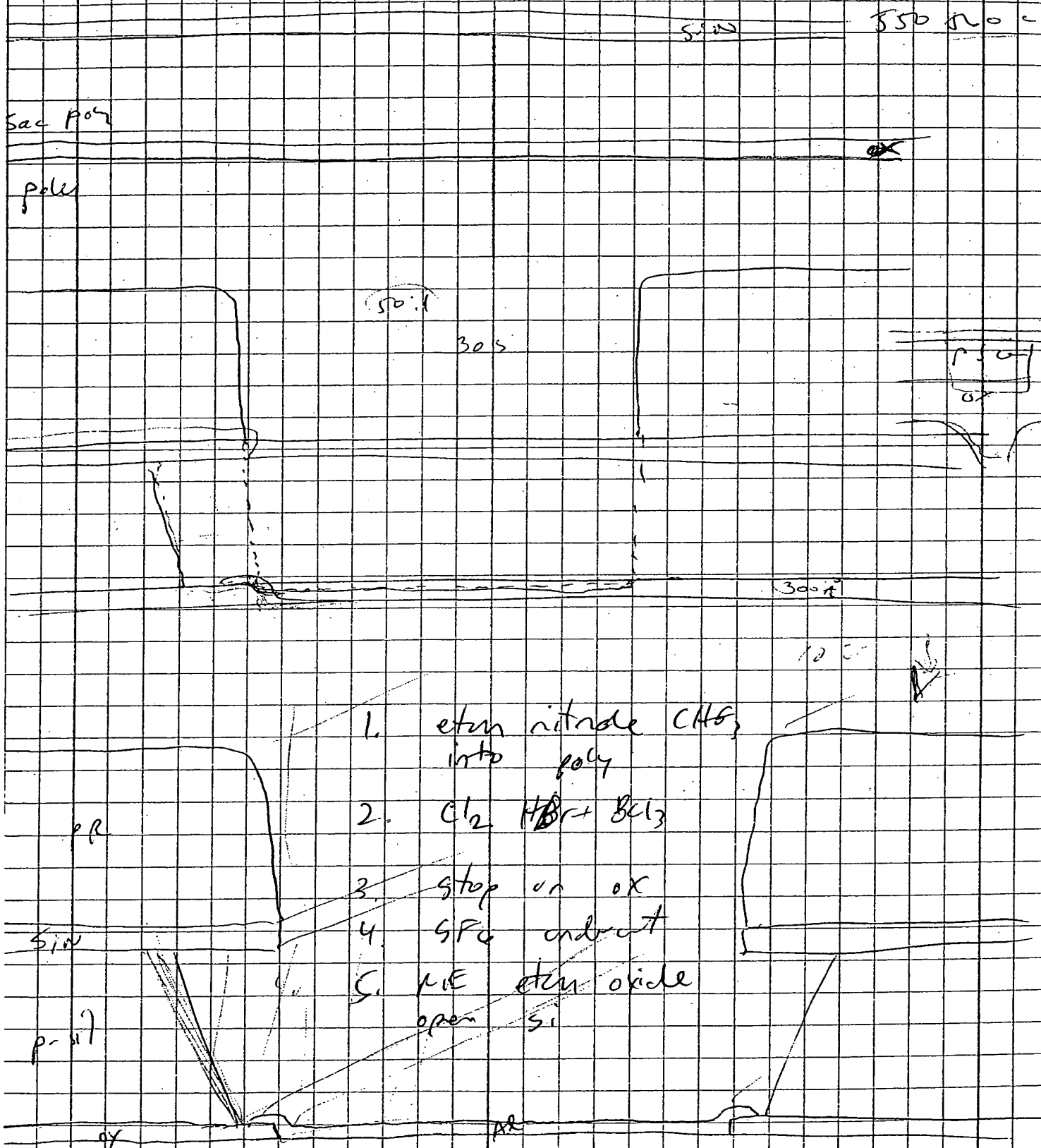
① need to
go out &
fill 20

BEST AVAILABLE COPY



7/29

ϕ order process flow ideas



1. etch nitride CH₃₇ into poly
2. Cl₂ HBr + BCl₃
3. stop on ox
4. SiO₂ conduct
5. p-R etch oxide open Si

bban P.R.

Ribbon F.R.

S; N

Sac poly.

P-Si

"Vic" or charge pit
mask

SIN

SIN

P-Si

← oxide
etch stop

stop coverage?

- extra mask.

contact out of optical area

LM1

POST

 $\gamma \text{ LA}$

u2

M3-field

Rib

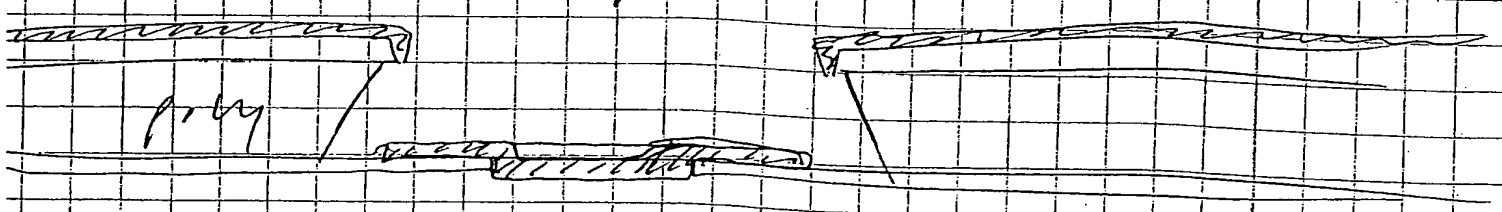
Seal

0. order design

processing to this identical metal layer just prior



ribbon mask + etch
short release
maybe add via mask tech
at over



ultra